

| Subst. Form PTO-1449 INFORMATION DISCLOSURE CITATION IN AN APPLICATION (Use several sheets if necessary) | | | | Docket Number (Optional) 56247-235 (CSLL-662CP) | Application Number 10/642,315 | | |
|--|-----|---|---------|---|---|----------|----------------------------|
| O I P E OCT 20 2004 PATENT & TRADEMARK OFFICE U. S. Patent Documents | | | | Applicant Sawyer, et al. | Filing Date 8/15/2003 Group Art Unit | | |
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| EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP § 609; Draw line through citation if not in conformance and not considered. Include copy with next communication to applicant. | | | | | | | |